

Title (en)

DEVICE FOR PRODUCING MULTI-LAYER CIRCUIT BOARDS AND USE THEREOF IN A MULTI-LEVEL HEAT PRESS

Title (de)

VORRICHTUNG ZUR HERSTELLUNG VON MEHRSCHEIDIGEN LEITERPLATTEN UND DEREN VERWENDUNG IN EINER ETAGEN-HEIZPRESSE

Title (fr)

DISPOSITIF POUR PRODUIRE DES CARTES DE CIRCUITS IMPRIMÉS MULTICOUCHES ET LEUR UTILISATION DANS UNE PRESSE À CHAUD À ÉTAGES

Publication

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Application

**EP 22797268 A 20220912**

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Abstract (en)

[origin: WO2023041111A1] The invention relates to a device for producing multi-layer circuit boards, comprising a multi-part tool having a tool lower part (2) and a tool upper part (1), wherein, in the intended use of the tool, multiple functional layers (5) and at least one insulating layer (4) of a multi-layer circuit board to be produced are arranged between the tool lower part (2) and the tool upper part (1), and comprising at least one measuring transducer, wherein the measuring transducer is provided between the tool upper part (1) and the tool lower part (2) and is in contact with at least one functional layer (5) and/or an insulating layer (4) of the multi-layer circuit board to be produced, characterised in that: a tool logic module (7) and a measurement value transmission module (12) with a receiving unit (9) and with a transmission unit (10) cooperating with the receiving unit (9) are provided, wherein the tool logic module (7) is retained on the tool and designed for receiving measurement values of the measuring transducer and wherein the tool logic module (7) has a transmitter, which is designed for the wireless forwarding of the measurement values and/or data obtained from same to the receiving unit (9) of the measurement value transmission module (12); a data line (14) is provided, leading from the transmission unit (10) of the measurement value transmission module (12) to a primary manufacturing control unit (13); and the transmission unit (10) is designed for transmitting on the measurement values received from the receiving unit (9) and/or the data obtained from same, via the data line (14), to the primary manufacturing control unit (13). The invention also relates to the use of the device in a multi-level heat press.

IPC 8 full level

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